**DORNPACKAGE** 

SDAS038C - DECEMBER 1982 - REVISED DECEMBER 1994

- Generate Either Odd or Even Parity for Nine Data Lines
- Cascadable for n-Bit Parity
- Can Be Used to Upgrade Existing Systems Using MSI Parity Circuits
- Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic (N) 300-mil DIPs

#### (TOP VIEW) G **□** ∨<sub>CC</sub> нΠ 13 [] F 2 ис П 3 12 ПΕ Пο ı 4 11 Σ EVEN [] 5 10 ∏ C 9 **∏** B $\Sigma$ ODD **GND** ПΑ 8

#### NC - No internal connection

#### description

These universal 9-bit parity generators/checkers utilize advanced Schottky high-performance

circuitry and feature odd ( $\Sigma$  ODD) and even ( $\Sigma$  EVEN) outputs to facilitate operation of either odd- or even-parity applications. The word-length capability is easily expanded by cascading.

These devices can be used to upgrade the performance of most systems utilizing the SN74ALS180 and SN74AS180 parity generators/checkers. Although the SN74ALS280 and SN74AS280 are implemented without expander inputs, the corresponding function is provided by the availability of an input (I) at terminal 4 and the absence of any internal connection at terminal 3. This permits the SN74ALS280 and SN74AS280 to be substituted for the SN74ALS180 and SN74AS180 in existing designs to produce an identical function even if the devices are mixed with existing SN74ALS180 and SN74AS180 devices.

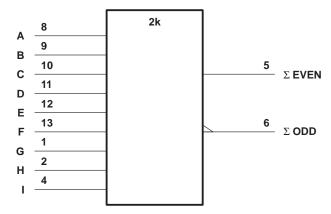
All SN74AS280 inputs are buffered to lower the drive requirements.

The SN74ALS280 and SN74AS280 are characterized for operation from 0°C to 70°C.

#### **FUNCTION TABLE**

NO. OF INPUTS	OUTI	PUTS
A – I THAT ARE HIGH	$\Sigma$ EVEN	$\Sigma$ ODD
0, 2, 4, 6, 8	Н	L
1, 3, 5, 7, 9	L	Н

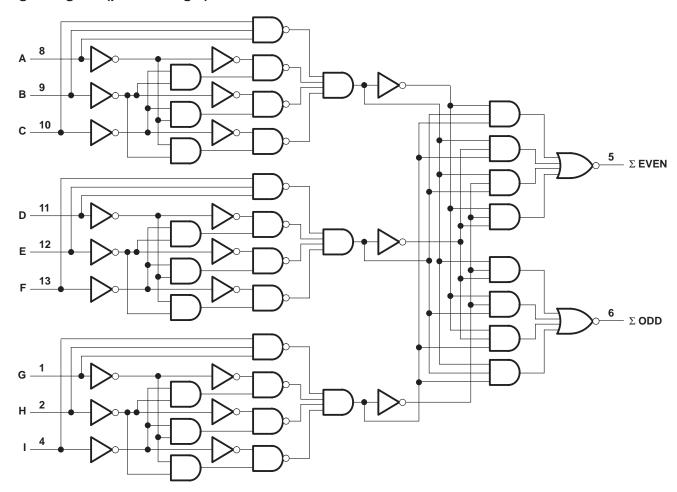
## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



#### logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
Operating free-air temperature range, T <sub>A</sub> : SN74ALS280	0°C to 70°C
Storage temperature range	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

		SN74ALS280			
		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			8.0	V
loh	High-level output current			-2.6	mA
l <sub>OL</sub>	Low-level output current			24	mA
TA	Operating free-air temperature	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			SN	74ALS2	80	UNIT	
PARAMETER	TEST CON	TEST CONDITIONS					
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.5	V	
, , , , , , , , , , , , , , , , , , ,	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2	!			
Voн	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -2.6 \text{ mA}$	2.4	3.3		V	
V	V 45V	I <sub>OL</sub> = 12 mA		0.25	0.4	V	
V <sub>OL</sub>	$V_{CC} = 4.5 \text{ V}$	I <sub>OL</sub> = 24 mA		0.35	0.5	V	
lį	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 7 V			0.1	mA	
lіН	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 2.7 V			20	μΑ	
I <sub>IL</sub>	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 0.4 V			-0.1	mA	
IO <sup>‡</sup>	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.25 V	-30		-112	mA	
Icc	$V_{CC} = 5.5 V$			10	16	mA	

### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 C <sub>L</sub> = 50 pF R <sub>L</sub> = 500 g T <sub>A</sub> = MIN t	<del>-</del> , 2,	UNIT	
			MIN	MAX	]	
<sup>t</sup> PLH	A	7 EVEN	3	20		
<sup>t</sup> PHL	Any	ΣEVEN	3	20	ns	
<sup>t</sup> PLH	Any	ΣODD	3	20	ns	
t <sub>PHL</sub>	Any	2 000	4	22	115	

<sup>§</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I<sub>OS</sub>.

## SN74ALS280, SN74AS280 9-BIT PARITY GENERATORS/CHECKERS

SDAS038C - DECEMBER 1982 - REVISED DECEMBER 1994

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

#### recommended operating conditions

		SN74AS280			
		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			8.0	V
lOH	High-level output current			-2	mA
l <sub>OL</sub>	Low-level output current			20	mA
TA	Operating free-air temperature	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445752		TEST CONDITIONS						
PARAMETER	TEST CON	IDITIONS	MIN TYP‡	MAX	UNIT			
VIK	$V_{CC} = 4.5 V,$	$I_{I} = -18 \text{ mA}$		-1.5	V			
VOH	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2		V			
VOL	$V_{CC} = 4.5 V,$	$I_{OL} = 20 \text{ mA}$	0.35	0.5	V			
ΙĮ	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 7 V		0.1	mA			
lін	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 2.7 V		20	μΑ			
I <sub>IL</sub>	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 0.4 V		-0.5	mA			
ΙΟ§	$V_{CC} = 5.5 V$ ,	V <sub>O</sub> = 2.25 V	-30	-112	mA			
Icc	V <sub>CC</sub> = 5.5 V		25	35	mA			

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C <sub>L</sub> = 50 pF R <sub>L</sub> = 500 Q T <sub>A</sub> = MIN t	2,	UNIT	
			MIN	MAX	1	
<sup>t</sup> PLH	A	2 EVEN	3	12		
<sup>t</sup> PHL	Any	ΣEVEN	3	11	ns	
tPLH	Any	ΣODD	3	12	nc	
<sup>t</sup> PHL	Any	2 000	3	11.5	ns	

 $<sup>\</sup>P$  For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

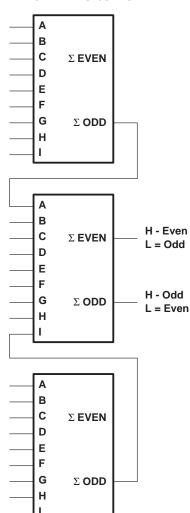


<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>§</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

#### **APPLICATION INFORMATION**

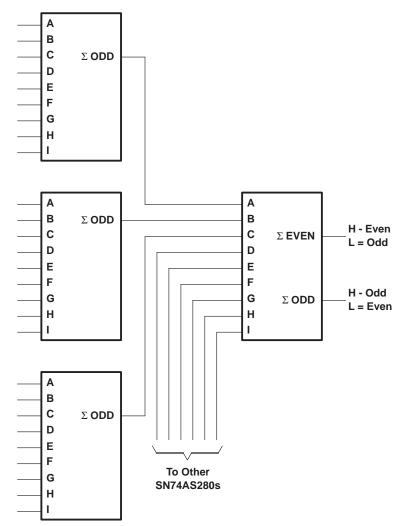
# 25-LINE PARITY GENERATOR/CHECKER



Three SN74ALS280/SN74AS280 devices can be used to implement a 25-line parity generator/checker.

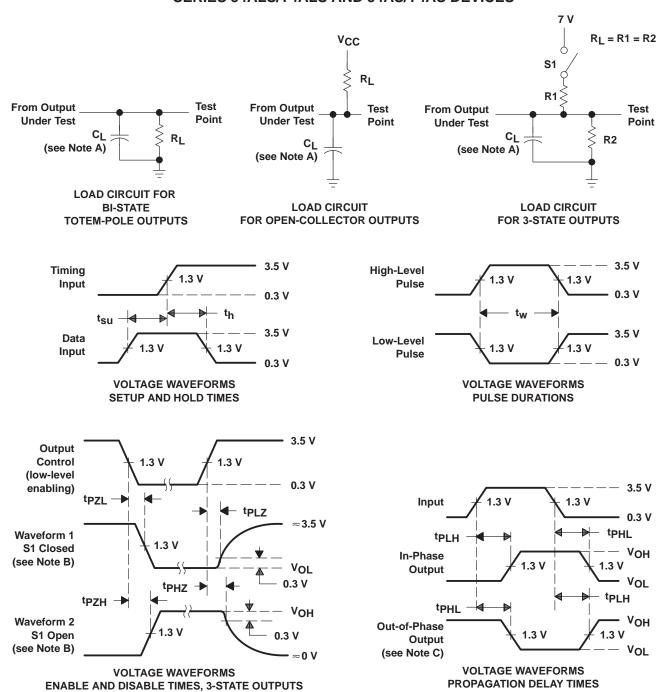
As an alternative, the  $\Sigma$  ODD outputs of two or three parity generators/checkers can be decoded with a 2-input ('AS86A or 'ALS86) exclusive-OR gate for 18- or 27-line parity applications.





Longer word lengths can be implemented by cascading SN74ALS280/SN74AS280 devices. Parity can be generated for word lengths up to 81 bits.

# PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_{\Gamma} = t_{f} = 2$  ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







10-Jun-2014

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS280N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74AS280D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS280	Samples
SN74AS280N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS280N	Samples
SN74AS280N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74AS280NSR	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS280	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



### **PACKAGE OPTION ADDENDUM**

10-Jun-2014

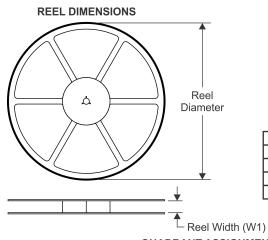
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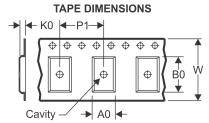
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**PACKAGE MATERIALS INFORMATION** 

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### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

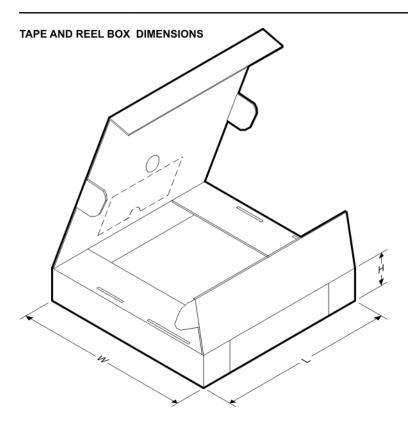
#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AS280NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AS280NSR	SO	NS	14	2000	367.0	367.0	38.0

# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

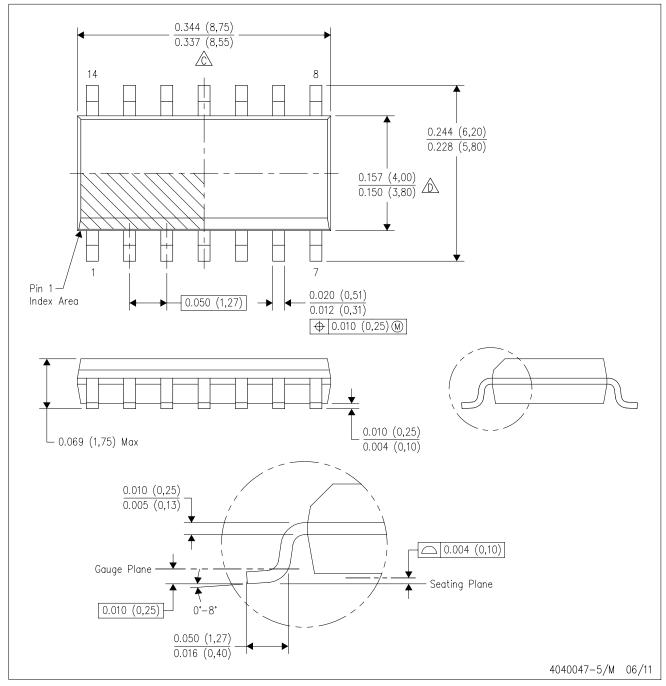


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDSO-G14)

### PLASTIC SMALL OUTLINE

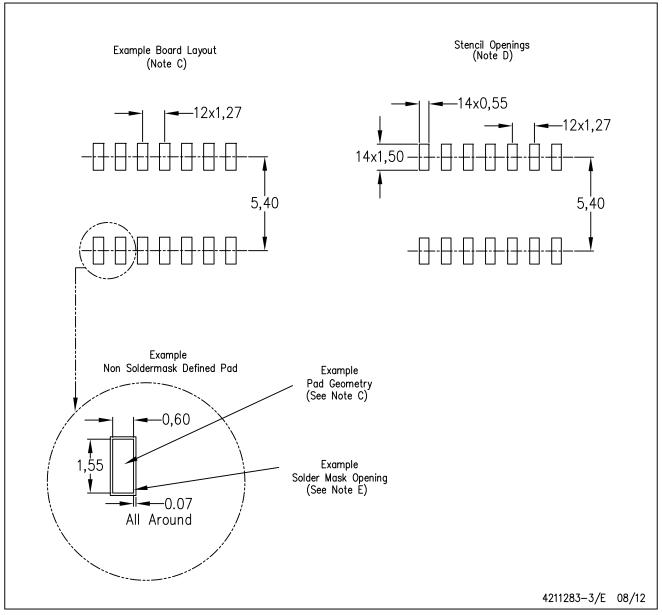


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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